☐ MN103SE5 Series

Туре	MN103SFE5P
Internal ROM type	FLASH
ROM (byte)	624K
RAM (byte)	32K
Package (Lead-free)	LQFP048-P2-0707A
Minimum Instruction Execution Time	20.9 ns (at 3.0 V to 3.6 V, 48 MHz)

■ Interrupts

RESET. IRQ \times 3. Timer \times 12. 1^2 C \times 7. SIF \times 8. DMA \times 12. Stream DMA \times 1. WDT. System error. USB \times 2. 12S \times 1

■ Timer Counter

8-bit timer \times 6

Reload-down count. Cascade connection possible (usable as a 16-bit to 32-bit timer)

16-bit timer \times 2

Up-down count. Input capture. PWM output. Compare/capture register 2 channnels

Watchdog timer × 1

■ Serial interface

Multi-master $I^2C \times 2$

UART/Synchronous interface selective × 4

■ Audio Output Interface

I2S interface × 1

■ DMA controller

Number of channels: 4 channels Unit of transfer: 8/16/32 bits Maximum transfer cycles: 65535

Starting factor: External interrupt. Timer. Serial transmission/reception. I²C transmission/reception. Software. USB transmission/reception

end. I2S empty

Transfer method: 2-bus cycle transfer

Adressing modes: Fixed. Increment. Decrement

Transfer mode: Word transfer. Burst transfer. Intermittent transfer

■ Stream DMA controller

Number of channels: 1 channels Unit of transfer: 8/32 bits Maximum transfer cycles: 65535 Transfer source: Interface RAM

Transfer destination: Serial I/F. Audio output interface

■ USB HOST Controller

Conforms to USB 2.0: Full-speed (12 Mbps) supported

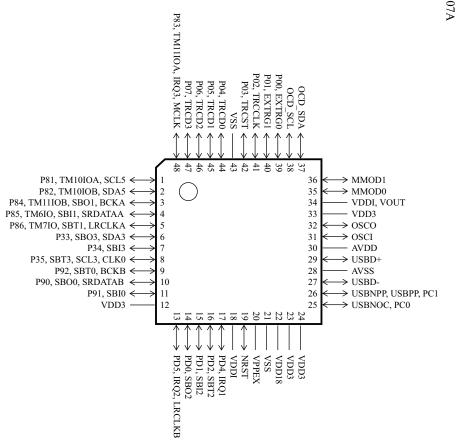
OHCI R1.0a standard conforming. External power supply control function. USB transceiver built-in

■ I/O Pins

I/O 27: (3 V I/O) Common use

Panasonic MAF00030DEM

■ Pin Assignment LQFP048-P2-0707A



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